

# Surface Mount Schottky Power Rectifier

## Plastic SOD-123 Package

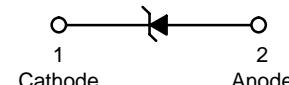
### Features and benefits

- Very small conduction losses
- Negligible switching losses
- Low forward voltage drop
- Surface mount device
- S- Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

**LBAT46T1G**  
**S-LBAT46T1G**



SOD-123



### Description

Diodes in the LBAT46T1G is high voltage, small signal Schottky diodes suited for protection and routing operations.

### Mechanical Characteristics

- Reel Options: LBAT46T1G = 3,000 per 7 "reel/8 mm tape
- Device Marking: Z46
- Polarity Designator: Cathode Band
- Weight: 11.7 mg (approximately)
- Case: Epoxy, Molded
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

### ORDERING INFORMATION

Device	Package	Shipping
LBAT46T1G S-LBAT46T1G	SOD-123	3000/Tape & Reel

### MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage		100	V
$I_F$	Continuous forward current		150	mA
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10 \text{ ms Sinusoidal}$	1	A
$T_{stg}$	Storage temperature range		-55 to +150	°C
$T_j$	Maximum operating junction temperature <sup>(1)</sup>		150	°C
$T_L$	Maximum soldering temperature <sup>(1)</sup>		260	°C

1. Pulse test:  $t_p = 380 \mu\text{s}$ ,  $\delta < 2 \%$

**LBAT46T1G,S-LBAT46T1G**
**THERMAL CHARACTERISTICS**

Symbol	Parameter	Value	Unit
$R_{th(j-a)}$	Junction to ambient <sup>(1)</sup>	500	°C/W

1. On epoxy printed circuit board with recommended pad layout

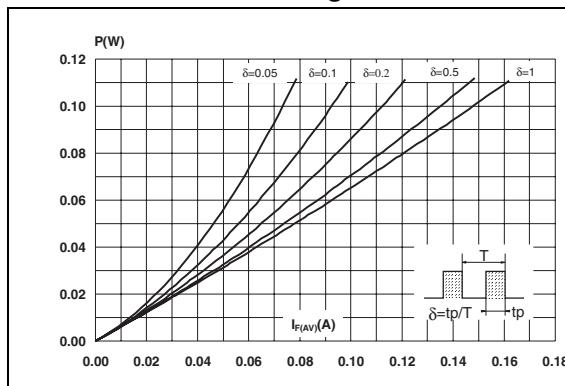
**ELECTRICAL CHARACTERISTICS**

Symbol	Parameter	Test conditions	Min.	Typ	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25^\circ C$	$V_R = 1.5 V$		0.5	$\mu A$
			$V_R = 10 V$		0.8	
			$V_R = 50 V$		2	
			$V_R = 75 V$		5	
		$T_j = 60^\circ C$	$V_R = 1.5 V$		5	
			$V_R = 10 V$		7.5	
			$V_R = 50 V$		15	
			$V_R = 75 V$		20	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25^\circ C$	$I_F = 0.1 mA$		0.25	$V$
			$I_F = 10 mA$		0.45	
			$I_F = 250 mA$		1	

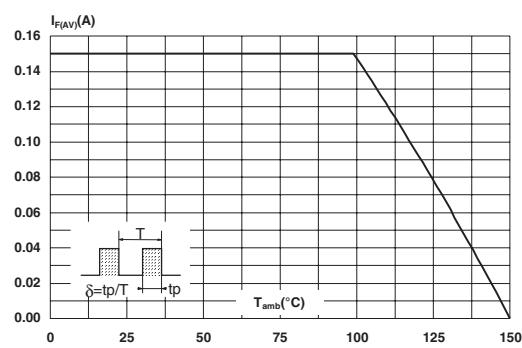
1. Pulse test:  $t_p = 5 ms$ ,  $\delta < 2 \%$   
 2. Pulse test:  $t_p = 380 \mu s$ ,  $\delta < 2 \%$

Symbol	Parameter	Test conditions	Min.	Typ	Max.	Unit
C	Diode capacitance	$V_R = 0 V$ , $F = 1 MHz$		10		$pF$
		$V_R = 1 V$ , $F = 1 MHz$		6		

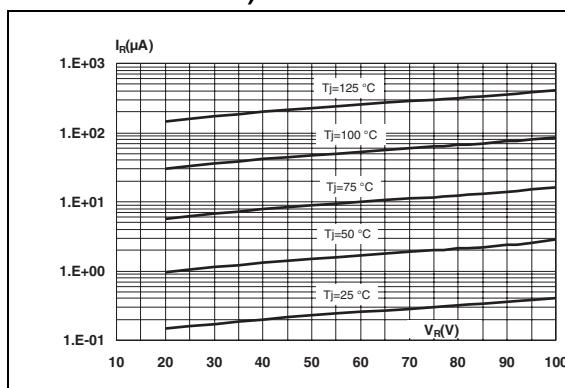
**Figure 1. Average forward power dissipation versus average forward current**



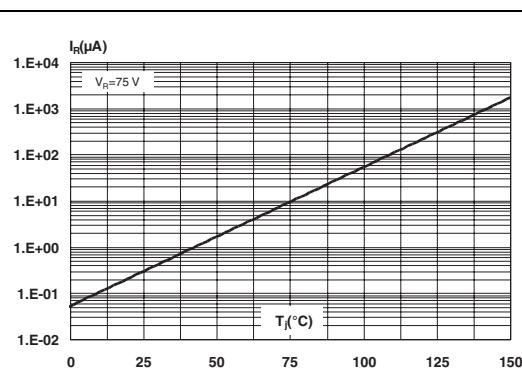
**Figure 2. Average forward current versus ambient temperature ( $\delta = 1$ )**



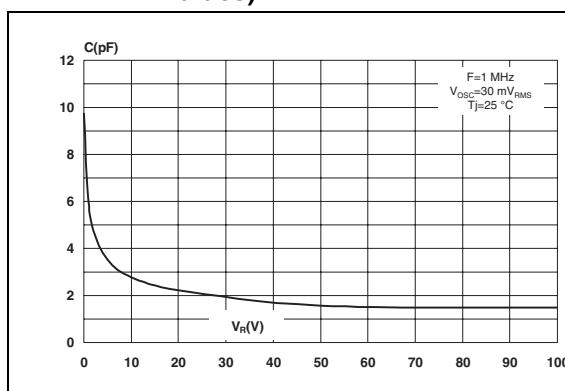
**Figure 3. Reverse leakage current versus reverse applied voltage (typical values)**



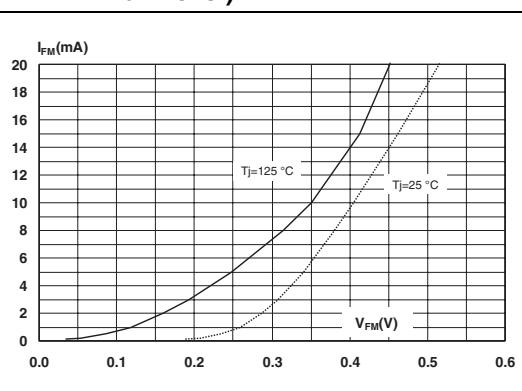
**Figure 4. Reverse leakage current versus junction temperature**

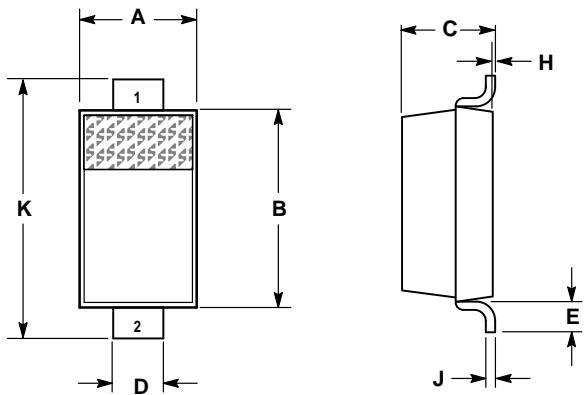


**Figure 5. Junction capacitance versus reverse applied voltage (typical values)**



**Figure 6. Forward voltage drop versus forward current (typical values, low-level)**

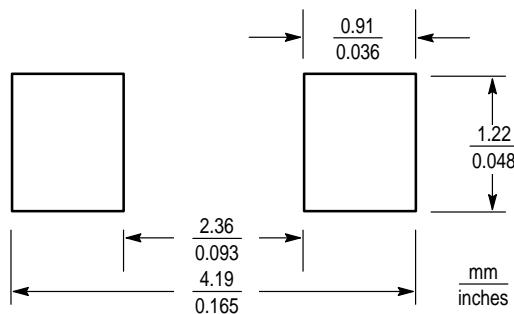


**PACKAGE DIMENSIONS**
**SOD-123**

**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.055	0.071	1.40	1.80
B	0.100	0.112	2.55	2.85
C	0.037	0.053	0.95	1.35
D	0.020	0.028	0.50	0.70
E	0.004	—	0.25	—
H	0.000	0.004	0.00	0.10
J	—	0.006	—	0.15
K	0.140	0.152	3.55	3.85

STYLE 1:  
PIN 1. CATHODE  
2. ANODE

**RECOMMENDED FOOTPRINT FOR SOD-123**

**SOD-123**